Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1.	(Currently Amended) An exposure method which illuminates method,
comprising:	
	illuminating a first object with an exposure beam and exposes beam; and
	exposing a second object with the exposure beam through the first object and a
projection optical-system, characterized in that system, wherein	
	at least a part of one of the first object and the projection optical system is
irradiated with	h a light beam having a wavelength range different from that of the exposure
beam through	a space waveguide mechanism, to correct an imaging characteristic of the
projection opt	ical system.

- 2. (Currently Amended) An exposure method as recited in claim 1, wherein characterized in that the space waveguide mechanism includes a hollow waveguide made of glass, ceramics, or metal.
- 3. (Currently Amended) An exposure method which illuminates method,

 comprising:

 illuminating a first object with an exposure beam and exposes beam; and

 exposing a second object with the exposure beam through the first object and a

 projection optical system, characterized in that wherein

at least a part of <u>one of</u> the first object and the projection optical system is irradiated with a light beam having a wavelength range different from that of the exposure beam and being in a predetermined polarization state through a polarization state control mechanism, to correct an imaging characteristic of the projection optical system.

- 4. (Currently Amended) An exposure method as recited in claim 3, wherein characterized in that the polarization state control mechanism includes a phase plate.
- 5. (Currently Amended) An exposure method which illuminates method, comprising:

<u>illuminating</u> a first object with an exposure beam and exposes beam; and

<u>exposing</u> a second object with the exposure beam through the first object and a

projection optical system, eharacterized in that wherein

at least a part of <u>one of</u> the first object and the projection optical system is irradiated with a light beam having a wavelength range different from that of the exposure beam and being in a predetermined polarization state through an optical guide and a polarization state control mechanism, to correct an imaging characteristic of the projection optical system.

- 6. (Currently Amended) An exposure method as recited in claim 5, wherein characterized in that the optical guide is a hollow fiber.
- 7. (Currently Amended) An exposure method as recited in elaims 5 or 6 claim 5, wherein eharacterized in that the polarization state control mechanism is a polarization plate.
- 8. (Currently Amended) An exposure method as recited in any one of claims 1 to 7, characterized in that claim 1, wherein

the light beam is generated by an RF excited waveguide type CO₂ laser.

9. (Currently Amended) An exposure method as recited in any one of claims 1 to 8, characterized in that claim 1, wherein

the at least the part of the <u>one of the</u> first object and the projection optical system is illuminated in a rotationally asymmetric light-quantity distribution with the exposure beam, and

the light beam is applied so as to correct a rotationally asymmetric aberration of the projection optical system generated by the irradiation of the exposure beam.

10. (Currently Amended) An exposure method as recited in claim 9, wherein characterized in that

a generated amount of the rotationally asymmetric aberration is calculated based on an irradiation amount of the exposure beam, and

the light beam is applied based on the calculated result.

11. (Currently Amended) A device production method including a lithography process characterized in that method, comprising:

<u>transferring</u> a pattern is transferred onto a photosensitive element in a <u>lithography process</u> using the exposure method as recited in any one of claims 1 to 10. <u>claim 1.</u>

12. (Currently Amended) An exposure apparatus which illuminates a first object on which a pattern for transfer is formed with an exposure beam and exposes a second object with the exposure beam through the first object and a projection optical system, characterized by-comprising:

an irradiation mechanism which irradiates at least a part of <u>one of</u> the first object and the projection optical system with a light beam having a wavelength range different from that of the exposure beam, wherein

the irradiation mechanism includes a space waveguide mechanism which guides the light beam along a predetermined optical path.

13. (Currently Amended) An exposure apparatus as recited in claim 12, characterized in that wherein

the space waveguide mechanism includes a hollow waveguide made of glass, ceramics, or metal.

14. (Currently Amended) An exposure apparatus which illuminates a first object on which a pattern for transfer is formed with an exposure beam and exposes a second object with the exposure beam through the first object and a projection optical system, eharacterized by-comprising:

an irradiation mechanism which irradiates at least a part of <u>one of</u> the first object and the projection optical system with a light beam having a wavelength range different from that of the exposure beam, wherein

the irradiation mechanism includes a polarization state control mechanism which sets a polarization state of the light beam to a predetermined state.

15. (Currently Amended) An exposure apparatus as recited in claim 14, whereincharacterized in that

the polarization state control mechanism includes a phase plate.

16. (Currently Amended) An exposure apparatus which illuminates a first object on which a pattern for transfer is formed with an exposure beam and exposes a second object with the exposure beam through the first object and a projection optical system, eharacterized by comprising:

an irradiation mechanism which irradiates at least a part of <u>one of</u> the first object and the projection optical system with a light beam having a wavelength range different from that of the exposure beam, wherein

the irradiation mechanism includes an optical guide which guides the light beam from a light source which generates the light beam, and a polarization state control mechanism which sets a polarization state of the light beam emitted from the optical guide to a predetermined state.

17. (Currently Amended) An exposure apparatus as recited in claim 16, whereincharacterized in that

the optical guide is a hollow fiber.

18. (Currently Amended) An exposure apparatus as recited in elaims 16 or 17, eharacterized in that claim 16, wherein

the polarization state control mechanism is a polarization plate.

19. (Currently Amended) An exposure apparatus as recited in any one of claims

12 to 18, characterized in that claim 12, wherein

the irradiation mechanism includes an RF excited waveguide type CO₂ laser as the light source which generates the light beam.

20. (Currently Amended) An exposure apparatus as recited in claim 19, whereineharacterized in that

the irradiation mechanism includes there are a plurality of the RF excited waveguide type CO₂ lasers.

21. (Currently Amended) A exposure apparatus as recited in any one of claims 12 to 20, characterized in that claim 12, wherein

the irradiation mechanism includes a first beam splitter which splits the light beam.

22. (Currently Amended) An exposure apparatus as recited in any one of claims 12 to 21, characterized in that claim 12, wherein

the irradiation mechanism includes at least one of a movable mirror and a shutter in order to time-divide the light beam.

23. (Currently Amended) An exposure apparatus as recited in any one of claims 12 to 22, characterized by claim 12, wherein further comprising:

a light source control unit which controls a light emitting duration of a light source which generates the light beam.

24. (Currently Amended) An exposure apparatus as recited in claim 13, wherein

an inner surface of the waveguide is coated with a reflective film including at least one of a metal film and a dielectric film in order to reflect the light beam.

25. (Currently Amended) An exposure apparatus as recited in any one of claims 12 to 24, characterized byclaim 12, further comprising:

a second beam splitter which divaricates a portion of the light beam, and beam; and a photoelectric sensor which receives the light divaricated by the second beam splitter, wherein

information on a light quantity of the light beam is obtained with the photoelectric sensor.

26. (Currently Amended) An exposure apparatus as recited in claim 25, characterized by further comprising:

at least one polarization element disposed between the light source of the light beam and the second beam splitter.

27. (Currently Amended) An exposure apparatus as recited in elaims 25 or 26, eharacterized byclaim 25, further comprising:

a 1/4 wavelength plate, disposed between the second beam splitter and an optical member constituting the projection optical system, which sets a polarization state of the light beam to a predetermined state.

28. (Currently Amended) An exposure apparatus as recited in any one of claims 12 to 27, characterized in that claim 12, wherein

the at least the part of the first object and the projection optical system is illuminated in a rotationally asymmetric light-quantity distribution with the exposure beam, and

the irradiation mechanism applies the light beam so as to correct a rotationally asymmetric aberration of the projection optical system generated by the illumination of the exposure beam.

29. (Currently Amended) An exposure apparatus as recited in claim 28, eharacterized by further comprising:

an aberration correction mechanism which corrects the rotationally symmetric aberration of the projection optical system, and

a control unit which controls operations of the irradiation mechanism and the aberration correction mechanism to correct an aberration of the projection optical system.

30. (Currently Amended) A device production-method including a lithography process, characterized in that method, comprising:

transferring a pattern is transferred onto a photosensitive element in the in a lithography process using the exposure apparatus as recited in any one of claims 12 to 29claim 12.